CLAIMS

1. A grinding tool for grinding a surface of a glass substrate for an electronic device, comprising:

grinding abrasive particles; a bonding material for bonding the grinding abrasive particles; and dispersion particles for dispersing a grinding pressure applied to the grinding abrasive particles, the dispersion particles being harder than the bonding material and softer than the grinding abrasive particles, wherein the grinding abrasive particles and the dispersion particles are dispersed and bonded in the bonding material;

wherein the total density of the grinding abrasive particles and the dispersion particles is within a range of 10 to 40 pieces/mm^2 on a grinding surface of the grinding tool.

2. The grinding tool according to claim 1, wherein the bonding material is a resin material.

3. The grinding tool according to claim 1 or 2, wherein the grinding abrasive particles are assembled abrasive particles in which a plurality of grinding abrasive particles are bonded with a fixing material.

4. The grinding tool according to any of claims 1 to 3, wherein the grinding abrasive particles include diamond abrasive particles.

5. The grinding tool according to any of claims 1 to 4, wherein the dispersion particles are made of alumina, ~~or~~ zirconia, or glass.

6. The grinding tool according to any of claims 1 to 5, wherein the dispersion particles are aggregates in which a plurality of dispersion particles are bonded with glass.

7. The grinding tool according to any of claims 1 to 6, wherein a proportion of the number of the dispersion particles with respect to the number of the grinding abrasive particles in the bonding material is such that 0.1 to 5

dispersion particles exist per grinding abrasive particle.

8. The grinding tool according to any of claims 1 to 7, wherein the grinding abrasive particles are assembled abrasive particles in which a plurality of grinding abrasive particles are bonded with a fixing material and the assembled abrasive particles have an average particle diameter of 30 to 50 μm.

9. The grinding tool according to any of claims 1 to 8, wherein the ratio of the average particle diameter of the dispersion particles with respect to the average particle diameter of the grinding abrasive particles falls within a range of 0.8 to 1.2.

10. A method for manufacturing a glass substrate, comprising grinding processing for grinding a main surface of a glass substrate for an electronic device by using the grinding tool according any of claims 1 to 9.

11. The method for manufacturing a glass substrate according to claim 10, wherein the glass substrate is a material for a magnetic-disk glass substrate.

12. ~~The~~ A method for manufacturing a magnetic-disk glass substrate, wherein at least polishing processing is carried out on a main surface of a glass substrate manufactured by the method according to claim 11.

13. A method for manufacturing a magnetic disk, wherein at least a magnetic recording layer is formed on a magnetic-disk glass substrate manufactured using the method for manufacturing a magnetic-disk glass substrate according to claim 12.